

CHAMBER ARRANGEMENTS, COATING SYSTEMS INCLUDING CHAMBER
ARRANGEMENTS, AND METHODS OF COATING WORKPIECES IN CHAMBER
ARRANGEMENTS AND COATING SYSTEMS

ABSTRACT

A chamber arrangement includes an outer chamber and an inner chamber. The outer chamber has a hollow interior. The inner chamber is sized and dimensioned for placement within the interior of the outer chamber and may seat therein a workpiece to form a coating onto the workpiece, such as a substrate support structure for a semiconductor processing system. An electrical connector is seated in a wall of the outer chamber and fluidly separates the interior of the outer chamber from an external environment outside of the outer chamber to provide an electrical communication between the workpiece and the external environment outside of the outer chamber, such as for heating the workpiece and/or controlling temperature of the workpiece during the forming of the coating onto the workpiece. Coating systems and methods of forming coatings are also described.

Fig. 2